<b>WEEQOO</b>		WEEQOO Multi	i-layer PCB Standa	rd Stackup
4-Layer PCB Board				
Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 18 um-plating to 35um
				PP 0.08 mm dielectric constant 4.29
			L2	
0.4mm±0.1mm	1/1oz			Core 0.2mm with 1/1 oz Cu
			L3	
				PP 0.08 mm dielectric constant 4.29
TULL	0	01.111	L4	Copper 18 um—plating to 35um
Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 18 um-plating to 35um PP 0.11 mm dielectric constant 4.29
		10000	L2	11 0.11 min dissective constant 4.29
0.6mm±0.1mm	1/1oz	11111	LZ	Core 0.2mm with 1/1 oz Cu
0.01111120.111111	17102	11111	L3	0010 0.2.him with 1/1 02 00
		00000		PP 0.11 mm dielectric constant 4.29
			L4	Copper 18 um–plating to 35um
			L1	Copper 18 um–plating to 35um
				PP 0.11 mm dielectric constant 4.29
		10000	L2	
0.6mm±0.1mm	1/1oz	00000		Core 0.3mm with 1/1 oz Cu
		11111	L3	
				PP 0.11 mm dielectric constant 4.29
			L4	Copper 18 um-plating to 35um
			L1	Copper 50um(±5)um-plating to 70um
		-		PP 0.11 mm dielectric constant 4.29
			L2	
0.6mm±0.1mm	2/1oz	11111		Core 0.2mm with 1/1 oz Cu
		11111	L3	
				PP 0.11 mm dielectric constant 4.29
			L4	Copper 50um(±5)um-plating to 70um
Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
		A STATE OF THE STA	L1	Copper 18 um-plating to 35um PP 0.11 mm dielectric constant 4.29
		Anna de	L2	PP 0.11 mm diejectric constant 4.29
0.8mm±0.1mm	1/1oz	11111	LZ	Core 0.4mm with 1/1 oz Cu
0.01111120.111111	17102	10000	L3	0010 0.411111 WIGH 171 02 00
		11111	20	PP 0.11 mm dielectric constant 4.29
		2	L4	Copper 18 um–plating to 35um
			L1	Copper 50um(±5)um-plating to 70um
		A		PP 0.11 mm dielectric constant 4.29
		10000	L2	
0.8mm±0.1mm	2/1oz	11111		Core 0.4mm with 1/1 oz Cu
		00000	L3	
		11111		PP 0.11 mm dielectric constant 4.29
		4 9	L4	Copper 50um(±5)um-plating to 70um
			L1	Copper 18 um–plating to 35um
				PP 0.18 mm dielectric constant 4.29
		10000	L2	
0.8mm±0.1mm	1/1oz	10000		Core 0.3mm with 1/1 oz Cu
			L3	
				PP 0.18 mm dielectric constant 4.29
			L4	Copper 18 um—plating to 35um
			L1	Copper 50um(±5)um-plating to 70um
		400000		PP 0.22 mm dielectric constant 4.29
			L2	
	244 =			0 00 111 1 711 7
0.8mm±0.1mm	2/1.5oz	*****		Core 0.2mm with 1.5/1.5 oz Cu
0.8mm±0.1mm	2/1.5oz	*****	L3	
0.8mm±0.1mm	2/1.5oz	*****		Core 0.2mm with 1.5/1.5 oz Cu  PP 0.22 mm dielectric constant 4.29  Copper 50um(±5)um-plating to 70um

Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 18 um-plating to 35um
				PP 0.11 mm dielectric constant 4.29
		10000	L2	
1.0mm±0.1mm	1/1oz	10000		Core 0.6mm with 1/1 oz Cu
		11111	L3	
		00000		PP 0.11 mm dielectric constant 4.29
			L4	Copper 18 um-plating to 35um
			L1	Copper 50um(±5)um-plating to 70um
				PP 0.11 mm dielectric constant 4.29
		10000	L2	
1.0mm±0.1mm	2/1oz	10000		Core 0.6mm with 1/1 oz Cu
		11111	L3	
				PP 0.11 mm dielectric constant 4.29
			L4	Copper 50um(±5)um-plating to 70um
			L1	Copper 50um(±5)um-plating to 70um
				PP 0.22 mm dielectric constant 4.29
		11111	L2	
1.0mm±0.1mm	2/1.5oz	10000		Core 0.4mm with 1.5/1.5 oz Cu
			L3	
				PP 0.22 mm dielectric constant 4.29
			1.4	
			L4	Copper 50um(±5)um-plating to 70um
Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Copper 50um(±5)um-plating to 70um  Laminated chart Thickness
Thickness	Copper thick (outer/inner)	StackUp		
Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness Copper 18 um-plating to 35um
Thickness 1.2mm±10%	Copper thick (outer/inner)	StackUp	Layer No. L1	Laminated chart Thickness Copper 18 um-plating to 35um
		StackUp	Layer No. L1	Laminated chart Thickness  Copper 18 um-plating to 35um  PP 0.11 mm dielectric constant 4.29
		StackUp	Layer No. L1 L2	Laminated chart Thickness  Copper 18 um-plating to 35um  PP 0.11 mm dielectric constant 4.29
		StackUp	Layer No. L1  L2  L3  L4	Laminated chart Thickness  Copper 18 um-plating to 35um  PP 0.11 mm dielectric constant 4.29  Core 0.8mm with 1/1 oz Cu
		StackUp	Layer No. L1 L2 L3	Laminated chart Thickness  Copper 18 um—plating to 35um  PP 0.11 mm dielectric constant 4.29  Core 0.8mm with 1/1 oz Cu  PP 0.11 mm dielectric constant 4.29  Copper 18 um—plating to 35um  Copper 50um(±5)um-plating to 70um
		StackUp	Layer No. L1  L2  L3  L4  L1	Laminated chart Thickness  Copper 18 um—plating to 35um  PP 0.11 mm dielectric constant 4.29  Core 0.8mm with 1/1 oz Cu  PP 0.11 mm dielectric constant 4.29  Copper 18 um—plating to 35um
1.2mm±10%	1/1oz	StackUp	Layer No. L1  L2  L3  L4	Laminated chart Thickness  Copper 18 um—plating to 35um  PP 0.11 mm dielectric constant 4.29  Core 0.8mm with 1/1 oz Cu  PP 0.11 mm dielectric constant 4.29  Copper 18 um—plating to 35um  Copper 50um(±5)um-plating to 70um  PP 0.11 mm dielectric constant 4.29
		StackUp	Layer No.  L1  L2  L3  L4  L1  L2	Laminated chart Thickness  Copper 18 um—plating to 35um  PP 0.11 mm dielectric constant 4.29  Core 0.8mm with 1/1 oz Cu  PP 0.11 mm dielectric constant 4.29  Copper 18 um—plating to 35um  Copper 50um(±5)um-plating to 70um
1.2mm±10%	1/1oz	StackUp	Layer No. L1  L2  L3  L4  L1	Laminated chart Thickness  Copper 18 um—plating to 35um  PP 0.11 mm dielectric constant 4.29  Core 0.8mm with 1/1 oz Cu  PP 0.11 mm dielectric constant 4.29  Copper 18 um—plating to 35um  Copper 50um(±5)um-plating to 70um  PP 0.11 mm dielectric constant 4.29  Core 0.8mm with 1/1 oz Cu
1.2mm±10%	1/1oz	StackUp	Layer No.  L1  L2  L3  L4  L1  L2  L3	Laminated chart Thickness  Copper 18 um—plating to 35um  PP 0.11 mm dielectric constant 4.29  Core 0.8mm with 1/1 oz Cu  PP 0.11 mm dielectric constant 4.29  Copper 18 um—plating to 35um  Copper 50um(±5)um-plating to 70um  PP 0.11 mm dielectric constant 4.29
1.2mm±10%	1/1oz	StackUp	Layer No.  L1  L2  L3  L4  L1  L2  L3  L4  L1  L2  L3	Laminated chart Thickness  Copper 18 um—plating to 35um  PP 0.11 mm dielectric constant 4.29  Core 0.8mm with 1/1 oz Cu  PP 0.11 mm dielectric constant 4.29  Copper 18 um—plating to 35um  Copper 50um(±5)um-plating to 70um  PP 0.11 mm dielectric constant 4.29  Core 0.8mm with 1/1 oz Cu  PP 0.11 mm dielectric constant 4.29  Copper 50um(±5)um-plating to 70um
1.2mm±10%	1/1oz	StackUp	Layer No.  L1  L2  L3  L4  L1  L2  L3	Laminated chart Thickness  Copper 18 um—plating to 35um  PP 0.11 mm dielectric constant 4.29  Core 0.8mm with 1/1 oz Cu  PP 0.11 mm dielectric constant 4.29  Copper 18 um—plating to 35um  Copper 50um(±5)um-plating to 70um  PP 0.11 mm dielectric constant 4.29  Core 0.8mm with 1/1 oz Cu  PP 0.11 mm dielectric constant 4.29  Copper 50um(±5)um-plating to 70um  Copper 50um(±5)um-plating to 70um  Copper 50um(±5)um-plating to 70um
1.2mm±10%	1/1oz	StackUp	Layer No.  L1  L2  L3  L4  L1  L2  L3  L4  L1  L1  L2  L3	Laminated chart Thickness  Copper 18 um—plating to 35um  PP 0.11 mm dielectric constant 4.29  Core 0.8mm with 1/1 oz Cu  PP 0.11 mm dielectric constant 4.29  Copper 18 um—plating to 35um  Copper 50um(±5)um-plating to 70um  PP 0.11 mm dielectric constant 4.29  Core 0.8mm with 1/1 oz Cu  PP 0.11 mm dielectric constant 4.29  Copper 50um(±5)um-plating to 70um
1.2mm±10% 1.2mm±10%	1/1oz 2/1oz	StackUp	Layer No.  L1  L2  L3  L4  L1  L2  L3  L4  L1  L2  L3	Laminated chart Thickness  Copper 18 um—plating to 35um  PP 0.11 mm dielectric constant 4.29  Core 0.8mm with 1/1 oz Cu  PP 0.11 mm dielectric constant 4.29  Copper 18 um—plating to 35um  Copper 50um(±5)um-plating to 70um  PP 0.11 mm dielectric constant 4.29  Core 0.8mm with 1/1 oz Cu  PP 0.11 mm dielectric constant 4.29  Copper 50um(±5)um-plating to 70um  Copper 50um(±5)um-plating to 70um  Copper 50um(±5)um-plating to 70um  PP 0.22 mm dielectric constant 4.29
1.2mm±10%	1/1oz	StackUp	Layer No.  L1  L2  L3  L4  L1  L2  L3  L4  L1  L1  L2  L3	Laminated chart Thickness  Copper 18 um—plating to 35um  PP 0.11 mm dielectric constant 4.29  Core 0.8mm with 1/1 oz Cu  PP 0.11 mm dielectric constant 4.29  Copper 18 um—plating to 35um  Copper 50um(±5)um-plating to 70um  PP 0.11 mm dielectric constant 4.29  Core 0.8mm with 1/1 oz Cu  PP 0.11 mm dielectric constant 4.29  Copper 50um(±5)um-plating to 70um  Copper 50um(±5)um-plating to 70um  Copper 50um(±5)um-plating to 70um
1.2mm±10% 1.2mm±10%	1/1oz 2/1oz	StackUp	Layer No.  L1  L2  L3  L4  L1  L2  L3  L4  L1  L1  L2  L3	Laminated chart Thickness  Copper 18 um—plating to 35um  PP 0.11 mm dielectric constant 4.29  Core 0.8mm with 1/1 oz Cu  PP 0.11 mm dielectric constant 4.29  Copper 18 um—plating to 35um  Copper 50um(±5)um-plating to 70um  PP 0.11 mm dielectric constant 4.29  Core 0.8mm with 1/1 oz Cu  PP 0.11 mm dielectric constant 4.29  Copper 50um(±5)um-plating to 70um  Copper 50um(±5)um-plating to 70um  Copper 50um(±5)um-plating to 70um  PP 0.22 mm dielectric constant 4.29
1.2mm±10% 1.2mm±10%	1/1oz 2/1oz	StackUp	Layer No.  L1  L2  L3  L4  L1  L2  L3  L4  L1  L2  L3  L4  L1  L2  L3	Laminated chart Thickness  Copper 18 um—plating to 35um  PP 0.11 mm dielectric constant 4.29  Core 0.8mm with 1/1 oz Cu  PP 0.11 mm dielectric constant 4.29  Copper 18 um—plating to 35um  Copper 50um(±5)um-plating to 70um  PP 0.11 mm dielectric constant 4.29  Core 0.8mm with 1/1 oz Cu  PP 0.11 mm dielectric constant 4.29  Copper 50um(±5)um-plating to 70um  Copper 50um(±5)um-plating to 70um  Copper 50um(±5)um-plating to 70um  PP 0.22 mm dielectric constant 4.29

Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 18 um-plating to 35um
		-		PP 0.11 mm dielectric constant 4.29
			L2	
1.6mm±10%	1/1oz	11111		Core 1.2mm with 1/1 oz Cu
		10000	L3	
				PP 0.11 mm dielectric constant 4.29
			L4	Copper 18 um-plating to 35um
			L1	Copper 50um(±5)um-plating to 70um
		-		PP 0.11 mm dielectric constant 4.29
			L2	
1.6mm±10%	2/1oz	11111		Core 1.2mm with 1/1 oz Cu
		10000	L3	
				PP 0.11 mm dielectric constant 4.29
			L4	Copper 50um(±5)um-plating to 70um
			L1	Copper 50um(±5)um-plating to 70um
		40000		PP 0.22 mm dielectric constant 4.29
			L2	
1.6mm±10%	2/1.5oz	11111		Core 1mm with 1.5/1.5 oz Cu
		10000	L3	
				PP 0.22 mm dielectric constant 4.29
			L4	Copper 50um(±5)um-plating to 70um
Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 18 um-plating to 35um
		4		PP 0.18 mm dielectric constant 4.29
		11111	L2	
2.0mm±10%	1/1oz	11111		Core 1.6mm with 1/1 oz Cu
			L3	
				PP 0.18 mm dielectric constant 4.29
			L4	Copper 18 um-plating to 35um
			L1	Copper 50um(±5)um-plating to 70um
		1		PP 0.11 mm dielectric constant 4.29
		11111	L2	
2.0mm±10%	2/1oz	11111		Core 1.6mm with 1/1 oz Cu
		,,,,,	L3	
		10000		PP 0.11 mm dielectric constant 4.29
			L4	Copper 50um(±5)um-plating to 70um
			L1	Copper 50um(±5)um-plating to 70um
		100		PP 0.29 mm dielectric constant 4.29
		"	L2	
2.0mm±10%	2/1.5oz	11111		Core 1.2mm with 1.5/1.5 oz Cu
		11111	L3	
		00000		PP 0.29 mm dielectric constant 4.29
			L4	Copper 50um(±5)um-plating to 70um
Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 18 um-plating to 35um
				PP 0.18 mm dielectric constant 4.29
		22000	L2	
2.4mm±10%	1/1oz	11111		Core 2mm with 1/1 oz Cu
	17102	10001	L3	
		11111		PP 0.18 mm dielectric constant 4.29
			L4	Copper 18 um-plating to 35um
			L1	Copper 50um(±5)um-plating to 70um
		And the second		PP 0.18 mm dielectric constant 4.29
			L2	
2.4mm±10%	2/1oz	11111		Core 2mm with 1/1 oz Cu
		,,,,,,	L3	
		10000		PP 0.18 mm dielectric constant 4.29
		4	L4	Copper 50um(±5)um-plating to 70um
			L1	Copper 50um(±5)um-plating to 70um
		(A)		PP 0.36 mm dielectric constant 4.29
		12000	L2	
	2/1.5oz	10000		Core 1.6mm with 1.5/1.5 oz Cu
2.4mm±10%				
2.4mm±10%	2/1.502	10001	L3	
2.4mm±10%	2/1.502	11111	L3	PP 0.36 mm dielectric constant 4.29

Note: The above is the standard stackup of WEEQOO's 4-layer PCB board,we may change the layer stackup according to latest material or technology. For more details The custom stackup is available, feel free to contact us via service@weeqoo.com.

6-Layer PCB Boar	d			
Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 18 umplating to 35um
				PP 0.11 mm dielectric constant 4.29
		11111	L2	
		4444		Core 0.2mm with 1/1 oz Cu
		4444	L3	
0.8mm ±0.1mm	1/1oz			PP 0.11 mm dielectric constant 4.29
10.111111		00000	L4	
		00000		Core 0.2mm with 1/1 oz Cu
		11111	L5	
				PP 0.11 mm dielectric constant 4.29
			L6	Copper 18 umplating to 35um
Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 18 umplating to 35um
		4		PP 0.18 mm dielectric constant 4.29
		111111	L2	
		00000		Core 0.2mm with 1/1 oz Cu
		4444	L3	
1.0mm ±0.1mm	1/1oz	4444		PP 0.18 mm dielectric constant 4.29
		4	L4	
				Core 0.2mm with 1/1 oz Cu
		4 4 2 4 4	L5	
		4		PP 0.18 mm dielectric constant 4.29
			L6	Copper 18 umplating to 35um
			L1	Copper 50um(±5)um-plating to 70um
		1		PP 0.11 mm dielectric constant 4.29
		-	L2	
				Core 0.2mm with 1/1 oz Cu
4.0		00000	L3	
1.0mm ±0.1mm	2/1oz	00000		PP 0.22 mm dielectric constant 4.29
		00000	L4	
		00000		Core 0.2mm with 1/1 oz Cu
		11111	L5	
				PP 0.11 mm dielectric constant 4.29
			L6	Copper 50um(±5)um-plating to 70um
Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 18 umplating to 35um
				PP 0.11 mm dielectric constant 4.29
		10000	L2	
		00000		Core 0.4mm with 1/1 oz Cu
		00000	L3	
1.2mm±10%	1/1oz	11111		PP 0.11 mm dielectric constant 4.29
		The state of the s	L4	
				Core 0.4mm with 1/1 oz Cu
			L5	
				PP 0.11 mm dielectric constant 4.29
			L6	Copper 18 umplating to 35um

Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 50um(±5)um-plating to 70um
				PP 0.18 mm dielectric constant 4.29
		11111	L2	
		4444		Core 0.2mm with 1/1 oz Cu
			L3	
1.2mm±10%	2/1oz	00000		PP 0.18 mm dielectric constant 4.29
		00000	L4	
		00000		Core 0.2mm with 1/1 oz Cu
		11111	L5	
				PP 0.18 mm dielectric constant 4.29
			L6	Copper 50um(±5)um-plating to 70um
Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 50um(±5)um-plating to 70um
				PP 0.22 mm dielectric constant 4.29
		11111	L2	
		4444		Core 0.2mm with 1.5/1.5 oz Cu
			L3	
1.2mm±10%	2/1.5oz			PP 0.22 mm dielectric constant 4.29
		00000	L4	
		00000		Core 0.2mm with 1.5/1.5 oz Cu
		11111	L5	
				PP 0.22 mm dielectric constant 4.29
			L6	Copper 50um(±5)um-plating to 70um
Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 18 umplating to 35um
				PP 0.11 mm dielectric constant 4.29
		111111	L2	
		11111		Core 0.6mm with 1/1 oz Cu
		4444	L3	
1.6mm±10%	1/1oz			PP 0.11 mm dielectric constant 4.29
			L4	
				Core 0.6mm with 1/1 oz Cu
		44444	L5	
				PP 0.11 mm dielectric constant 4.29
			L6	Copper 18 umplating to 35um
Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 50um(±5)um-plating to 70um
				PP 0.18 mm dielectric constant 4.29
		10000	L2	
		00000		Core 0.4mm with 1/1 oz Cu
		00000	L3	
1.6mm±10%	2/1oz	11111		PP 0.18 mm dielectric constant 4.29
			L4	
		4		Core 0.4mm with 1/1 oz Cu
			L5	
		7		PP 0.18 mm dielectric constant 4.29
l			L6	Copper 50um(±5)um-plating to 70um

Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 50um(±5)um-plating to 70um
				PP 0.22 mm dielectric constant 4.29
		11111	L2	
		4444		Core 0.4mm with 1.5/1.5 oz Cu
			L3	
1.6mm±10%	2/1.5oz	00000		PP 0.22 mm dielectric constant 4.29
		00000	L4	
		00000		Core 0.4mm with 1.5/1.5 oz Cu
		11111	L5	
				PP 0.22 mm dielectric constant 4.29
			L6	Copper 50um(±5)um-plating to 70um
Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 18 umplating to 35um
				PP 0.11 mm dielectric constant 4.29
		11111	L2	
		4444		Core 0.8mm with 1/1 oz Cu
			L3	
2.0mm±10%	1/1oz			PP 0.11 mm dielectric constant 4.29
		00000	L4	
		00000		Core 0.8mm with 1/1 oz Cu
		11111	L5	
				PP 0.11 mm dielectric constant 4.29
			L6	Copper 18 umplating to 35um
Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 50um(±5)um-plating to 70um
				PP 0.11 mm dielectric constant 4.29
		111111	L2	
		11111		Core 0.8mm with 1/1 oz Cu
		4444	L3	
2.0mm±10%	2/1oz			PP 0.11 mm dielectric constant 4.29
			L4	
				Core 0.8mm with 1/1 oz Cu
		44444	L5	
				PP 0.11 mm dielectric constant 4.29
			L6	Copper 50um(±5)um-plating to 70um
Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 50um(±5)um-plating to 70um
				PP 0.22 mm dielectric constant 4.29
		10000	L2	
		00000		Core 0.6mm with 1.5/1.5 oz Cu
		00000	L3	
2.0mm±10%	2/1.5oz	11111		PP 0.22 mm dielectric constant 4.29
			L4	
		4		Core 0.6mm with 1.5/1.5 oz Cu
			L5	
		7		PP 0.22 mm dielectric constant 4.29
	1		L6	Copper 50um(±5)um-plating to 70um

Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 18 umplating to 35um
				PP 0.11 mm dielectric constant 4.29
		and the	L2	
		4444		Core 1.0mm with 1/1 oz Cu
			L3	
2.4mm±10%	1/1oz			PP 0.11 mm dielectric constant 4.29
		00000	L4	
		00000		Core 1.0mm with 1/1 oz Cu
		11111	L5	
				PP 0.11 mm dielectric constant 4.29
			L6	Copper 18 umplating to 35um
Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 50um(±5)um-plating to 70um
				PP 0.11 mm dielectric constant 4.29
		mini.	L2	
		4444		Core 1.0mm with 1/1 oz Cu
			L3	
2.4mm±10%	2/1oz			PP 0.11 mm dielectric constant 4.29
		00000	L4	
		00000		Core 1.0mm with 1/1 oz Cu
		11111	L5	
				PP 0.11 mm dielectric constant 4.29
			L6	Copper 50um(±5)um-plating to 70um
Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 50um(±5)um-plating to 70um
		4		PP 0.22 mm dielectric constant 4.29
		11111	L2	
		11111		Core 0.8mm with 1.5/1.5 oz Cu
		and the	L3	
2.4mm±10%	2/1.5oz			PP 0.22 mm dielectric constant 4.29
		00000	L4	
		00000		Core 0.8mm with 1.5/1.5 oz Cu
		11111	L5	
				PP 0.22 mm dielectric constant 4.29
			L6	Copper 50um(±5)um-plating to 70um

Note: The above is the standard stackup of WEEQOO's 6-layer PCB board, we may change the layer stackup according to latest material or technology. For more details The custom stackup is available, feel free to contact us via service@weeqoo.com.

8-Layer PCB Board	l			
Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
	, ,		L1	Copper 18 umplating to 35um
				PP 0.11 mm dielectric constant 4.29
			L2	
				Core 0.2mm with 1/1 oz Cu
			L3	
		00000		PP 0.11 mm dielectric constant 4.29
		11111	L4	
1.0mm±0.1mm	1/1oz	00000		Core 0.2mm with 1/1 oz Cu
1.01111120.1111111	17102	11111	L5	0010 0.E11111 Wild 17 1 02 00
			20	PP 0.11 mm dielectric constant 4.29
			L6	TT 0.11 mm diction constant 4.25
		00000	LO	Core 0.2mm with 1/1 oz Cu
		11111	L7	Core 0.2mm with 1/1 02 Cu
			Li	PP 0.11 mm dielectric constant 4.29
			1.0	
Third cons	0	01-111-	L8	Copper 18 umplating to 35um
Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 18 umplating to 35um
		<u> </u>		PP 0.11 mm dielectric constant 4.29
			L2	
				Core 0.2mm with 1/1 oz Cu
		00000	L3	
		11111		PP 0.11 mm dielectric constant 4.29
			L4	
1.2mm±10%	1/1oz	00000		Core 0.2mm with 1/1 oz Cu
			L5	
		11111		PP 0.11 mm dielectric constant 4.29
		11111	L6	
				Core 0.2mm with 1/1 oz Cu
			L7	
				PP 0.11 mm dielectric constant 4.29
			L8	Copper 18 umplating to 35um
			L1	Copper 50um(±5)um-plating to 70um
		/		PP 0.11 mm dielectric constant 4.29
			L2	
		111111		Core 0.2mm with 1/1 oz Cu
		111111	L3	
				PP 0.11 mm dielectric constant 4.29
		0000	L4	
1.2mm±10%	2/1oz	00000		Core 0.2mm with 1/1 oz Cu
		11111	L5	
				PP 0.11 mm dielectric constant 4.29
		00000	L6	
		10000		Core 0.2mm with 1/1 oz Cu
		11111	L7	22.2 2.2 , , , , , , , , , ,
				PP 0.11 mm dielectric constant 4.29
			L8	Copper 50um(±5)um-plating to 70um
			Lo	Copper Souni(±3)um-plating to 70um

Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 18 umplating to 35um
				PP 0.18 mm dielectric constant 4.29
			L2	
				Core 0.2mm with 1/1 oz Cu
			L3	
				PP 0.18 mm dielectric constant 4.29
			L4	
1.6mm±10%	1/1oz	00000		Core 0.2mm with 1/1 oz Cu
		10000	L5	
		11111		PP 0.18 mm dielectric constant 4.29
			L6	
				Core 0.2mm with 1/1 oz Cu
			L7	
				PP 0.18 mm dielectric constant 4.29
			L8	Copper 18 umplating to 35um
			L1	Copper 50um(±5)um-plating to 70um
			1.0	PP 0.18 mm dielectric constant 4.29
			L2	0 - 0 0 - 11 4/4 - 0
		11111	L3	Core 0.2mm with 1/1 oz Cu
		111111	L3	PP 0.18 mm dielectric constant 4.29
		11111	L4	FF 0.16 mm delectric constant 4.29
1.6mm±10%	2/1oz	,,,,,	L-1	Core 0.2mm with 1/1 oz Cu
1.011111121070	2/102		L5	0010 0.211111 Will 1/1 02 00
		00000		PP 0.18 mm dielectric constant 4.29
			L6	
		11111		Core 0.2mm with 1/1 oz Cu
		0000	L7	
				PP 0.18 mm dielectric constant 4.29
			L8	Copper 50um(±5)um-plating to 70um
			L1	Copper 50um(±5)um-plating to 70um
				PP 0.22 mm dielectric constant 4.29
			L2	
		10000		Core 0.2mm with 1.5/1.5 oz Cu
		11111	L3	
				PP 0.22 mm dielectric constant 4.29
		00000	L4	
1.6mm±10%	2/1.5oz			Core 0.2mm with 1.5/1.5 oz Cu
		111111	L5	DD 0 00
		11111	10	PP 0.22 mm dielectric constant 4.29
		11111	L6	000
			1.7	Core 0.2mm with 1.5/1.5 oz Cu
		00000	L7	DD 0.22 mm dialoctric constant 4.20
			1.0	PP 0.22 mm dielectric constant 4.29
			L8	Copper 50um(±5)um-plating to 70um

Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 18 umplating to 35um
				PP 0.18 mm dielectric constant 4.29
			L2	
		11111		Core 0.4mm with 1/1 oz Cu
			L3	
				PP 0.18 mm dielectric constant 4.29
		00000	L4	
2.0mm±10%	1/1oz	00000		Core 0.4mm with 1/1 oz Cu
		11111	L5	
		11111		PP 0.18 mm dielectric constant 4.29
			L6	
				Core 0.4mm with 1/1 oz Cu
		00000	L7	
				PP 0.18 mm dielectric constant 4.29
			L8	Copper 18 umplating to 35um
			L1	Copper 50um(±5)um-plating to 70um
		/ 2	1.0	PP 0.18 mm dielectric constant 4.29
			L2	004
			L3	Core 0.4mm with 1/1 oz Cu
		00000	Lo	PP 0.18 mm dielectric constant 4.29
		11111	L4	FF 0.16 IIIII dielectric constant 4.29
2.0mm±10%	2/1oz	11111	L4	Core 0.4mm with 1/1 oz Cu
2.01111121070	2/102		L5	0010 0.4mm wat 1/1 02 00
				PP 0.18 mm dielectric constant 4.29
		00000	L6	
		00000		Core 0.4mm with 1/1 oz Cu
		00000	L7	
				PP 0.18 mm dielectric constant 4.29
			L8	Copper 50um(±5)um-plating to 70um
			L1	Copper 50um(±5)um-plating to 70um
				PP 0.19 mm dielectric constant 4.29
			L2	
		11111		Core 0.4mm with 1.5/1.5 oz Cu
		11111	L3	
		11111		PP 0.19 mm dielectric constant 4.29
			L4	
2.0mm±10%	2/1.5oz	00000		Core 0.4mm with 1.5/1.5 oz Cu
		11111	L5	DD 0.40
		11111	10	PP 0.19 mm dielectric constant 4.29
		11111	L6	004
			1.7	Core 0.4mm with 1.5/1.5 oz Cu
			L7	DD 0.10 mm dialogtic
			1.0	PP 0.19 mm dielectric constant 4.29
			L8	Copper 50um(±5)um-plating to 70um

Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 18 umplating to 35um
				PP 0.11 mm dielectric constant 4.29
			L2	
		111111		Core 0.6mm with 1/1 oz Cu
		11111	L3	
				PP 0.11 mm dielectric constant 4.29
			L4	
2.4mm±10%	1/1oz	00000		Core 0.6mm with 1/1 oz Cu
		10000	L5	
		00000		PP 0.11 mm dielectric constant 4.29
		11111	L6	
		4		Core 0.6mm with 1/1 oz Cu
			L7	
				PP 0.11 mm dielectric constant 4.29
			L8	Copper 18 umplating to 35um
			L1	Copper 50um(±5)um-plating to 70um
		/ 7		PP 0.11 mm dielectric constant 4.29
			L2	
				Core 0.4mm with 1/1 oz Cu
		00000	L3	
		11111		PP 0.11 mm dielectric constant 4.29
			L4	
2.4mm±10%	2/1oz			Core 0.6mm with 1/1 oz Cu
			L5	
		00000		PP 0.11 mm dielectric constant 4.29
		11111	L6	
				Core 0.6mm with 1/1 oz Cu
			L7	
				PP 0.11 mm dielectric constant 4.29
			L8	Copper 50um(±5)um-plating to 70um
			L1	Copper 50um(±5)um-plating to 70um
		4		PP 0.29 mm dielectric constant 4.29
			L2	
				Core 0.4mm with 1.5/1.5 oz Cu
		00000	L3	
		11111		PP 0.29 mm dielectric constant 4.29
			L4	
2.4mm±10%	2/1.5oz			Core 0.4mm with 1.5/1.5 oz Cu
		11111	L5	
		00000		PP 0.29 mm dielectric constant 4.29
		11111	L6	
				Core 0.4mm with 1.5/1.5 oz Cu
			L7	
				PP 0.29 mm dielectric constant 4.29
			L8	Copper 50um(±5)um-plating to 70um

Note: The above is the standard stackup of WEEQOO's 8-layer PCB board,we may change the layer stackup according to latest material or technology. For more detailsThe custom stackup is available, feel free to contact us via service@weeqoo.com.